



Material Content Data Sheet



Sales Product Name				IPD048N06L3 G		Issued		26. August 2018	
MA#				MA001662064					
Package				PG-TO252-3-311		Weight*		315.14 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	3.393	1.08	1.08	10767	10767	
leadframe	inorganic material	phosphorus	7723-14-0	0.043	0.01		136		
	non noble metal	iron	7439-89-6	0.143	0.05		455		
	non noble metal	copper	7440-50-8	143.098	45.41	45.47	454078	454669	
	non noble metal	aluminium	7429-90-5	4.166	1.32	1.32	13219	13219	
wire	inorganic material	antimonytrioxide	1309-64-4	1.936	0.61		6143		
encapsulation	plastics	brominated resin	-	2.074	0.66		6582		
	organic material	carbon black	1333-86-4	2.213	0.70		7021		
	plastics	epoxy resin	-	18.668	5.92		59238		
	inorganic material	silicondioxide	60676-86-0	113.392	35.98	43.87	359814	438798	
leadfinish	non noble metal	tin	7440-31-5	3.740	1.19	1.19	11868	11868	
plating	inorganic material	phosphorus	7723-14-0	0.000	0.00		1		
	non noble metal	nickel	7440-02-0	0.086	0.03	0.03	274	275	
solder	non noble metal	tin	7440-31-5	0.060	0.02		189		
	noble metal	silver	7440-22-4	0.075	0.02		237		
	non noble metal	lead	7439-92-1	2.850	0.90	0.94	9045	9471	
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		18		
	non noble metal	iron	7439-89-6	0.019	0.01		61		
	non noble metal	copper	7440-50-8	19.177	6.09	6.10	60854	60933	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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